1987
- Dr. Morris Chang founds TSMC, pioneering the pure-play foundry business model

1988
- Establishes North American subsidiary – TSMC North America

1989
- Establishes European subsidiary – TSMC Europe

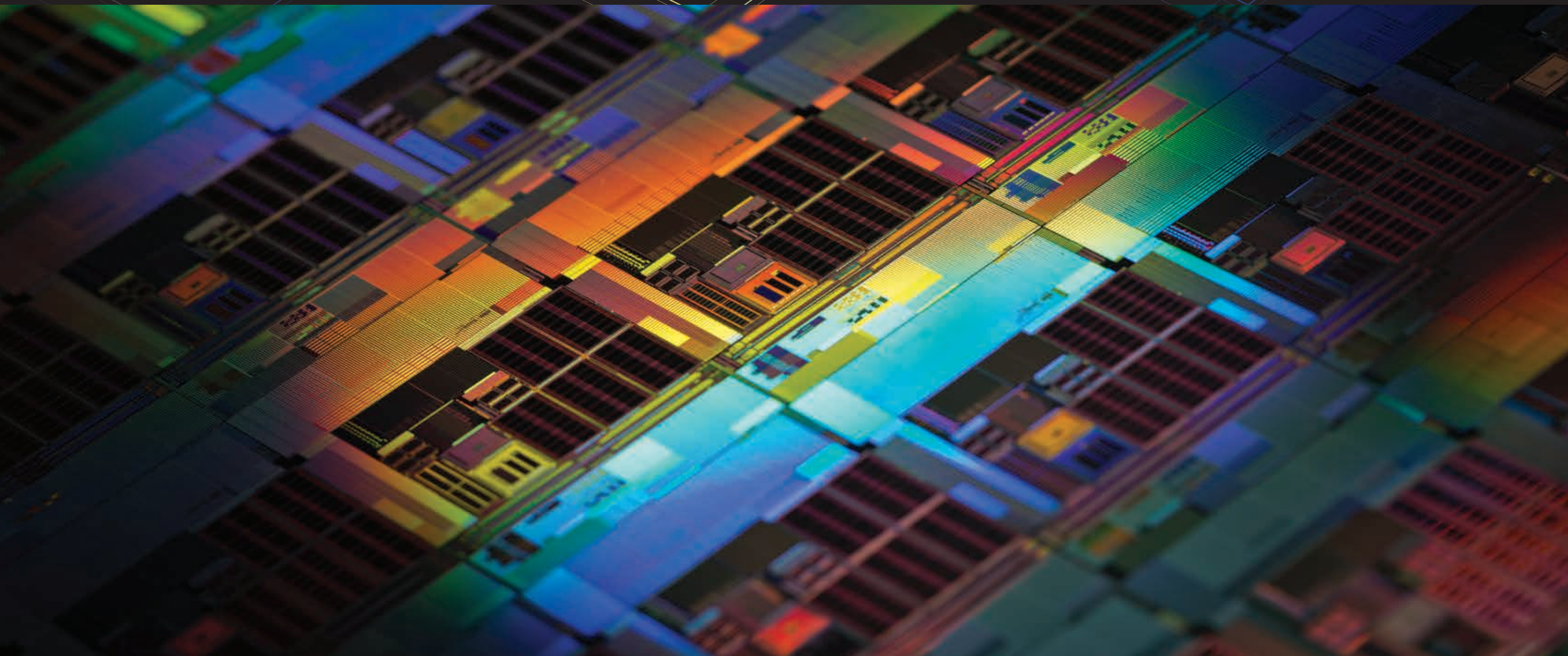
1994
- TSMC's ordinary shares are listed on the Taiwan Stock Exchange

1995
- Establishes WaferTech, a joint venture with long-term customers and the first pure-play foundry company in the United States

1996
- Proposes "Virtual Fab" as company's vision

1997
- Establishes Japanese subsidiary – TSMC Japan KK

1998
- Establishes the TSMC Education and Culture Foundation



2. Company Profile

2.1 An Introduction to TSMC

Established in 1987 and headquartered in Hsinchu Science Park, Taiwan, TSMC pioneered the pure-play foundry business model with an exclusive focus on manufacturing customers' products. By choosing not to design, manufacture or market any semiconductor products under its own name, the Company ensures that it never competes with its customers. Based on this founding principle, the key to TSMC's success has always been to focus on its customers' success. TSMC's foundry business model has enabled the rise of the global fabless industry, and, since its inception, TSMC has been the world's leading semiconductor foundry. In 2021, the Company manufactured 12,302 different products using 291 distinct technologies for 535 different customers.

TSMC-made semiconductors serve a global customer base that is large and diverse with a wide range of applications. These products are used in a variety of end markets including smartphones, high performance computing, the Internet of Things (IoT), automotive, and digital consumer electronics. Such strong diversification helps to smooth fluctuations in demand, which in turn allows TSMC to maintain higher levels of capacity utilization and profitability, and generate healthy returns for future investment.

The annual capacity of the manufacturing facilities managed by TSMC and its subsidiaries exceeded 13 million 12-inch equivalent wafers in 2021. These facilities include four 12-inch wafer GIGAFAB® fabs, four 8-inch wafer fabs, and one 6-inch wafer fab – all in Taiwan – as well as one 12-inch wafer fab at a wholly owned subsidiary, TSMC Nanjing Company Limited, and two 8-inch wafer fabs at wholly owned subsidiaries, WaferTech in the United States and TSMC China Company Limited.

In December 2021, TSMC established a subsidiary, Japan Advanced Semiconductor Manufacturing, Inc. (JASM), in Kumamoto, Japan, with Sony Semiconductor Solutions Corporation and DENSO Corporation participating as minority shareholders. JASM will construct and operate a fab that utilizes 12/16- and 22/28-nanometer technology to address strong global market demand for specialty technologies. Production is targeted to begin by the end of 2024.

Meanwhile, the Company continued to execute its plan for an advanced semiconductor fab in Arizona, the United States, with production targeted for 2024.

TSMC provides customer support, account management and engineering services through offices in North America, Europe, Japan, China, and South Korea. At the end of 2021, the Company and its subsidiaries employed more than 65,000 people worldwide.

The Company is listed on the Taiwan Stock Exchange (TWSE) under ticker number 2330, and its American Depositary Shares (ADSs) are traded on the New York Stock Exchange (NYSE) under the symbol TSM.

2.2 Market/Business Summary

2.2.1 TSMC Achievements

In 2021, TSMC maintained its leading position in the foundry segment of the global semiconductor industry by accounting for 26% of the worldwide semiconductor market excluding memory, an increase from 24% in 2020. TSMC's growth was mainly driven by the continued expansion of 5G and high performance computing (HPC)-related applications.

The Company's strong market position stems in great part from its leadership in advanced process technologies. In 2021, 50% of TSMC's wafer revenue came from advanced manufacturing processes – defined as geometries of 7nm and smaller – up from 41% in 2020.

TSMC offers comprehensive technology portfolio and continues to invest in advanced technologies, specialty technologies, and advanced packaging and silicon stacking technologies, to provide customers more added value.

In addition to its leadership in advanced process and specialty technologies, TSMC offers 3DFabric™, a comprehensive family of 3D silicon stacking and advanced packaging technologies to complement its process technology offerings. 3DFabric™ provides customers greater chip design flexibility to unleash innovation and is another differentiating competitive advantage for the Company.

2.2.2 Market Overview

TSMC estimates that the worldwide semiconductor market excluding memory reached US$447 billion in revenue in 2021, representing a 25% increase from 2020. In the foundry segment of the semiconductor industry, total revenue rose to US$102 billion in 2021, a robust growth over 2020.

2.2.3 Industry Outlook, Opportunities and Threats

Foundry Industry Demand and Supply Outlook

In 2021, TSMC's solid growth in the foundry segment was fueled by strong, broad based market demand. Industry megatrends, such as 5G, artificial intelligence (AI) proliferation, and the accelerating digital transformation, drove increased demand across all major markets: smartphones, high performance computing (HPC), Internet of Things (IoT), and automotive. During this time, to cope with high demand amid supply uncertainties, the electronics supply chain took on higher inventory levels, which also contributed to foundry segment and TSMC growth.

For 2022, the industry megatrends are likely to continue and hence TSMC sees healthy increases in overall demand for electronic devices in general, resulting in projected growth in the low-teens for the worldwide semiconductor market excluding memory. For the longer term, fueled by increasing semiconductor content in most electronic devices, continued market share gains by fabless companies, increases in integrated device manufacturer (IDM) outsourcing, and the expanding use of in-house application-specific integrated circuits (ASIC) by systems companies, TSMC expects foundry segment revenue to outpace the high single-digit compound annual growth rate projected for the worldwide semiconductor market excluding memory from 2021 through 2026.

As an upstream supplier in the semiconductor supply chain, the foundry segment is tightly correlated with the market health of the major platforms including smartphones, HPCs, the IoT, automotive, and digital consumer electronics (DCE).

• Smartphones

Despite the severe impact of the COVID-19 pandemic, smartphone unit shipments grew 6% in 2021, reflecting accelerated 5G commercialization, as new 5G smartphones shortened the overall replacement cycle. As this trend continues, TSMC projects low-single-digit growth for the smartphone market in 2022. Over the longer term, the migration to 5G, together with improved performance, longer battery life, biosensors and more AI features will all continue to propel smartphone sales going forward.

High performance and power efficient integrated circuit (IC) technology is an essential requirement among handset manufacturers, while highly integrated chips and advanced 3D packaging design are the preferred solutions to optimize cost, power and form factor (IC footprint and thickness). Spurred by the need for higher performance to run AI applications, various complex software computations and higher resolution video, the migration to advanced process technologies will certainly continue. TSMC is an acknowledged leader in process technology for manufacturing highly integrated chips and advanced 3D packaging designs and as such is very well positioned to serve the smartphone market.

• High Performance Computing (HPC)

The HPC platform includes PCs, tablets, game consoles, servers, base stations and more. Major HPC unit shipments grew 10% in 2021, driven by the COVID-19 pandemic "stay at home economy", server and data center upgrade cycle to accommodate rapidly growing data traffic and to fulfill the expanding needs of AI applications, and continued 5G base station deployment.

Following its strong performance in 2021, HPC unit shipment growth is projected to be low-single-digit in 2022. However, the accelerated-digitalization stimulated by COVID-19 pandemic had induced a structural increase in HPC-related semiconductor demand. As industry embarks upon the 5G era, an increasingly intelligent and more connected world will fuel massive requirements for computation power as well as a great need for energy-efficient computing. All these require higher performance and more power-efficient CPUs, GPUs, NPUs, AI accelerators, and related-ASICs, which will drive the overall HPC platform towards richer silicon content, more advanced process technologies, and advanced 3D packaging. These trends are all favorable to TSMC, given our technology leadership in these areas.

• Internet of Things (IoT)

The IoT platform includes various types of connected devices, such as smart wearables, smart speakers, smart health devices, home automation devices, surveillance systems, smart city, and smart manufacturing. Boosted by the digital transformation, IoT unit shipments grew 30% in 2021, with home automation devices, smart watches and smart health devices as the major growth drivers.

These same drivers are expected to continue their momentum in 2022, leading to a larger than 20% growth in IoT unit shipments. In addition, the COVID-19 pandemic continues to change consumers' life and work styles, spurring more applications for smart home and health management, while the enterprises also accelerate digital transformation, driving the demand for enterprise IoT devices. By adding more AI functions, IoT devices are becoming more intelligent IoT devices and further drive demand for more powerful yet lower power-consuming controllers, connectivity ICs and sensors. In addition to offering the industry's most leading technology, TSMC also offers customers ultra-low power process technologies to meet industry trends and help them succeed in the marketplace.

• Automotive

Worldwide car unit sales grew 3% in 2021, driven by strong end-demand recovery but constrained by unexpected chip shortages and supply-chain disruptions caused by several natural disasters including a snowstorm in Texas, fire accident in Japan, as well as the COVID-19 resurgence in Southeast Asia. In 2022, global car unit sales are expected to post growth between high-single-digit to low-teens driven by the pent-up demand, improved semiconductor supply, and better supply chain management.

The entire automotive industry is moving in the direction towards "greener, safer, and smarter," which will accelerate the adoption of electric vehicles (EVs), advanced driver assistance systems (ADAS), and smart cockpit/infotainment systems. All these will lead to increased demand for AP/MCU/ASIC processors, in-car networking, sensors, and Power Management ICs, thus continuously increasing the silicon content per car. TSMC offers a wide variety of process technologies to enable customers to deliver competitive products in the automotive market.

• Digital Consumer Electronics (DCE)

TV demand, although stimulated by the COVID-19 pandemic "stay at home economy," was curtailed by the increased cost of TV panels, resulting in a 3% decline in unit shipments in 2021.

While set-top box (STB) demand, bolstered by 4K and HDR upgrades, grew in 2021, other consumer products such as digital cameras and cordless phones continued to decline due to stagnant demand and cannibalization by smartphones.

Overall, the DCE market is expected to decline low-single-digit in 2022, while certain higher-end segments such as mini-LED, OLED, high frame rate (HFR) 4K and smart TVs continue to show positive growth.

AI-enabled functions like picture quality enhancement, super resolution upscaling to 4K/8K, and voice control are increasingly incorporated in TVs. TSMC advanced technologies will continue to support customers in creating and differentiating their innovative products in this market.

Supply Chain

The electronics industry features a long and complex supply chain, the elements of which are correlated and highly interdependent. At the upstream manufacturing level, IC vendors need to have sufficient, flexible supply deliveries to handle fluctuating demand dynamics. Foundry vendors play an important role in maintaining the health and effectiveness of the supply chain. As a leader in the foundry segment, TSMC provides advanced technologies and large-scale capacity to complement and support the innovations created in the downstream chain.

2.2.4 TSMC Position, Differentiation and Strategy

Position

TSMC is a worldwide semiconductor foundry leader in advanced, specialty and advanced packaging technologies. In 2021, TSMC accounted for 26% of the worldwide semiconductor market excluding memory, an increase from 24% in 2020. Net revenue by geography, calculated mainly on the country in which customers are headquartered, was: 65% from North America; 14% from the Asia Pacific region, excluding China and Japan; 10% from China; 6% from Europe, the Middle East and Africa; and 5% from Japan. Net revenue by platform was: 44% from smartphones; 37% from the high performance computing (HPC); 8% from the Internet of Things (IoT); and 4% from automotive. In addition, 4% came from digital consumer electronics, while others accounted for the remaining 3%.

Differentiation

TSMC's leadership position is based on three defining competitive strengths and a business strategy rooted in the Company's heritage. The Company distinguishes itself from the competition through its technology leadership, manufacturing excellence and customer trust.

As a technology leader, TSMC is consistently first among dedicated foundries to provide next generation, leading-edge technologies. The Company also maintains a leadership position in more mature technologies by applying the lessons learned in leading-edge technology development to enrich its specialty technologies. Beyond process technology, TSMC has established frontend and backend integration capabilities to create the optimum power/performance/area "sweet spot" to help customer achieve faster time-to-production.

Well known for industry-leading manufacturing capabilities, TSMC extends its leadership through its Open Innovation Platform® (OIP) and Grand Alliance initiatives. The OIP initiative quickens the pace of innovation in the semiconductor design community and among its ecosystem partners, as well as in the Company's own IP, design implementation and design for manufacturing capabilities, process technology and backend services. A key element is a set of ecosystem interfaces and collaborative components initiated and supported by the Company that more efficiently empower innovation throughout the supply chain and drive the creation and sharing of new revenue and profits. The TSMC Grand Alliance is one of the most powerful forces for innovation in the semiconductor industry, bringing together customers, electronic design automation (EDA) partners, IP partners, and key equipment and material suppliers at a new, higher level of collaboration. Its objective is to help customers, alliance members and TSMC win business and improve competitiveness.

The foundation for customer trust is a commitment TSMC made when it opened for business in 1987 to never compete with its customers. In keeping this commitment, TSMC has never designed, manufactured or marketed any integrated circuits under its own name, but instead has focused all of its efforts and resources on becoming the trusted foundry for its customers.

Strategy

TSMC is confident that its differentiating strengths will enable it to prosper from the foundry segment's many attractive growth opportunities. For the five major markets, namely smartphones, high performance computing, the Internet of Things, automotive, and digital consumer electronics, and in response to the fact that the focus of customer demand is shifting from process-technology-centric to product-application-centric, the Company has constructed five corresponding technology platforms to provide customers with comprehensive and competitive logic process technologies, specialty technologies, IPs and packaging and testing technologies to shorten customers' time to design and time to market. These five platforms are:

Smartphone Platform: TSMC offers customers leading process technologies such as 4nm FinFET (N4) and 5nm FinFET (N5) logic process technologies, as well as comprehensive IPs for premium product applications to further enhance chip performance, reduce power consumption, and decrease chip size. For mainstream product applications, the Company offers a broad range of logic process technologies, including 6nm FinFET (N6), 7nm FinFET Plus (N7+), 7nm FinFET (N7), 12nm FinFET compact plus (12FFC+), 12nm FinFET compact (12FFC), 16nm FinFET compact plus (16FFC+), 16nm FinFET compact (16FFC), 28nm high performance compact (28HPC), 28nm high performance mobile compact plus (28HPC+), and 22nm ultra-low power (22ULP) logic process technologies, in addition to comprehensive IPs, to satisfy customer needs for high performance and low power chips. Furthermore, for premium and mainstream product applications, the Company offers highly competitive, leading-edge specialty technologies to deliver specialty companion chips for customers' logic application processors, including RF, embedded flash memory, emerging memory technologies, power management, sensors, and display chips, as well as advanced 3DFabric™ packaging technologies such as industry-leading Integrated Fan-Out (InFO) technology.

High Performance Computing (HPC) Platform: Driven by data explosion and application innovation, HPC has become one of the key growth drivers for TSMC's business. TSMC provides customers, both fabless IC design companies and system companies, with leading-edge process technologies such as N4, N5, N6, N7, and 12nm/16nm FinFET, as well as comprehensive IPs including high-speed interconnect IPs to meet customers' product requirements for transferring and processing vast amounts of data anywhere, anytime. In particular, TSMC introduced its first high performance computing (HPC)-focused technology, N4X, representing the ultimate performance and maximum clock frequencies in TSMC's 5-nanometer family. Based on advanced process nodes, a variety of HPC products have been launched, such as central processing units (CPUs), graphics processor units (GPUs), field programmable gate arrays (FPGAs), server processors, accelerators, high-speed networking chips, etc. These products can be used in current and future 5G, AI, cloud, and data centers. TSMC also offers multiple advanced 3DFabric™ packaging technologies, such as CoWoS®, InFO, and TSMC-SoIC™, to enable homogeneous and heterogeneous chip integration to meet customer requirements for high performance, high compute density and efficiency, low latency and high integration. TSMC will continue to optimize its high performance computing platform and strengthen collaboration with customers to help them capture market growth in HPC markets.

Internet of Things Platform: TSMC provides leading, comprehensive and highly integrated ultra-low power (ULP) technology platforms to enable innovations for artificial intelligence of things (AIoT) applications. The Company's offerings include the new FinFET-based 12-nanometer technology – N12e™ featuring energy efficiency with high performance that results in more computing power and AI inferencing, 22nm ultra-low leakage (ULL), 28nm ULP, 40nm ULP, and 55nm ULP, which have been widely adopted by various edge AI system-on-a-chip (SoC), and battery-powered applications. TSMC has also extended its low Vdd (low operating voltage) offerings with wide-range of operating voltage SPICE (simulation program with integrated circuit emphasis) models for extreme low-power applications. TSMC also offers competitive and comprehensive specialty technologies in RF, enhanced analog devices, embedded flash memory, emerging memory, sensors and display chips, as well as multiple 3DFabric™ advanced packaging technologies, including InFO technology to support the fast-growing demand in AIoT edge computing and wireless connectivity.

Automotive Platform: TSMC's Automotive Platform provides a comprehensive spectrum of technologies and services to support the three megatrends – safer, smarter and greener – in the automotive industry. The Company is also an industry leader in providing a robust automotive IP ecosystem, which covers 16nm FinFET and 7nm FinFET technologies and extends to 5nm FinFET technology, for advanced driver-assistance systems (ADAS), advanced in-vehicle infotainment (IVI), as well as zonal controllers for new electrical/electronic (E/E) architecture for the automotive industry. In addition to its advanced logic platform, TSMC offers a broad array of competitive specialty technologies, including 28nm embedded flash memory, 28nm, 22nm, and 16nm mmWave RF, high sensitivity CMOS Image/LiDAR (light detection and ranging) sensors, and power management ICs. Magnetic random access memory (MRAM), an emerging technology, has demonstrated automotive Grade-1 capability on 22nm and is under development with good progress on 16nm to meet automotive Grade-1 requirements. All these automotive technologies are applied to TSMC's automotive process qualification standards based on AEC-Q100 standards or meeting customers' technology specifications.

Digital Consumer Electronics (DCE) Platform: TSMC provides customers with leading, comprehensive technologies to deliver AI-enabled smart devices for DCE applications, including smart digital TVs (DTV), set-top boxes (STBs), AI-embedded smart cameras and associated wireless local area networks (WLAN), power management ICs (PMIC), timing controllers (T-CON) and so on. The Company's leading 7nm FinFET compact (7FFC), 16FFC/12FFC, 22ULP/22ULL and 28HPC+ technologies have been widely adopted by leading global makers of 8K/4K DTV, 4K streaming STB/over-the-top (OTT), digital single-lens reflex (DSLR) devices, and so on. TSMC will continue to make these technologies more cost competitive through die size shrink for customers' digital intensive chip designs and to drive lower power consumption for more cost-effective packaging.

TSMC continually strengthens its core competitiveness and deploys both short-term and long-term plans for technology and business development and assists customers in taking on the challenges of short product cycles and intense competition in the electronic products market to meet ROI and growth objectives.

- **Short-Term Semiconductor Business Development Plan**

1. Substantially ramp up the business and sustain advanced technology market share by continually increasing capacity and R&D investments.
2. Maintain mainstream technology market share by expanding business to new customers and market segments.
3. Continue to enhance the competitive advantages of the Company's technology platforms in smartphones, HPC, IoT, automotive, and digital consumer electronics to expand TSMC's dedicated foundry services in these product applications.
4. Further expand TSMC's business and service infrastructure into emerging and developing markets.

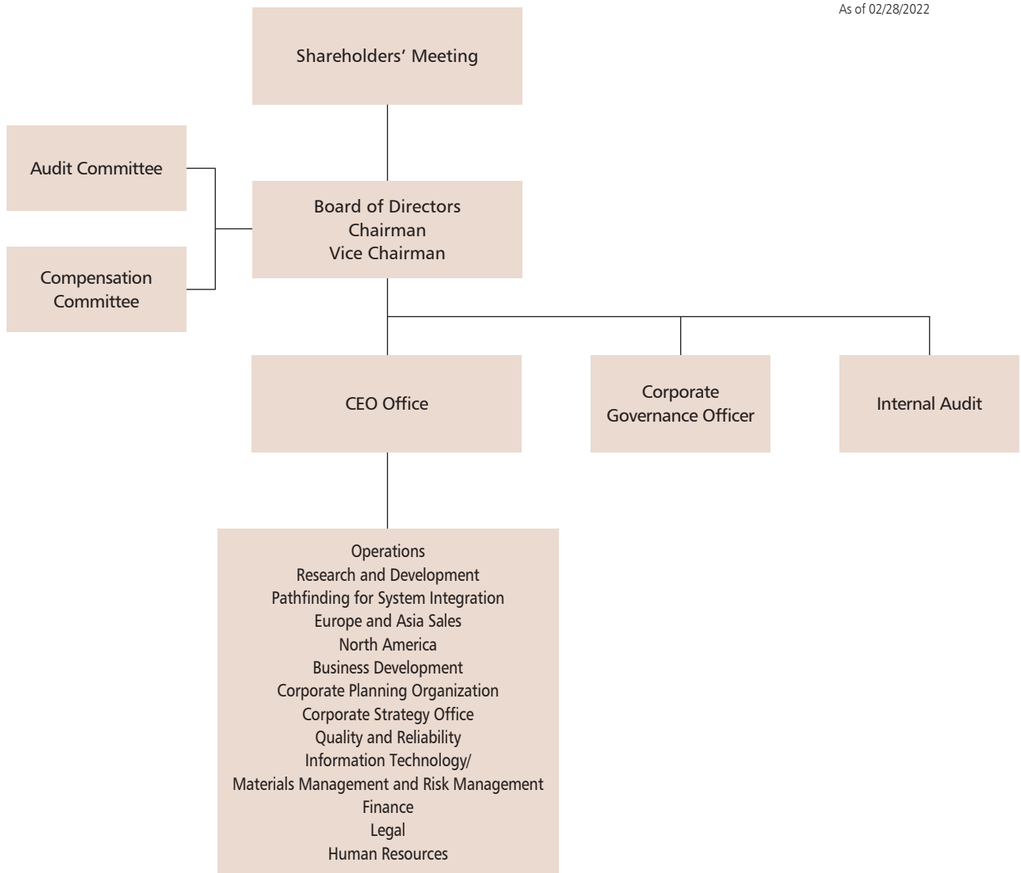
- **Long-Term Semiconductor Business Development Plan**

1. Continue developing leading-edge technologies at a pace consistent with the Moore's Law.
2. Broaden specialty business contributions by further developing derivative technologies.
3. Provide more integrated services, covering system-level integration design, design technology definition, design tool preparation, wafer processing, 3DFabric™ advanced packaging and silicon stacking technologies, and testing services, and so on, all of which deliver more value to customers through optimized solutions.

2.3 Organization

2.3.1 Organization Chart

As of 02/28/2022



2.3.2 Major Corporate Functions

Operations
- Includes managing all fabs in Taiwan and overseas; manufacturing technology development; product engineering, advanced packaging technology development, production and service integration

Research and Development
- Advanced technology development, exploratory research, and design and technology platform development, specialty technology development

Pathfinding for System Integration
- System Integration Technology Pathfinding

Europe and Asia Sales
- Customer business, technical marketing, and regional market development in Europe and Asia (China, Japan, South Korea and Taiwan); immediate and comprehensive technical support, as well as customer service including customers in North America.

North America
- Sales and market development, field technical solutions and business operations for customers in North America

Business Development
- Identification of market trends and new applications that shape the technology roadmap and portfolios for the Company; also provides key support in strengthening customer relationships along with Company branding management

Corporate Planning Organization
- Planning for operational resources, as well as for production and demand; integration of business processes, corporate pricing, market analysis and forecasting

Corporate Strategy Office
- Corporate strategy formation and implementation

Quality and Reliability
- Assurance of the quality and reliability of the Company's products by resolving issues at the developmental stage; improving and managing product quality at the production stage; providing solutions to customers' quality related issues; and providing services for advanced materials and failure analysis

Information Technology/Corporate Information Security
- Integration of the Company's technology and business IT systems; infrastructure development; communication services and assurance of IT security and service quality; implementing big data and machine learning to improve the Company's productivity and accelerate R&D delivery

Materials Management and Risk Management
- Procurement, warehousing, import and export, and logistics support; also environmental protection, industrial safety, occupational health and risk management

Internal Audit
- Inspection and review of the Company's internal control system, its adequacy in design and effectiveness in operation, with independent risk assessment to ensure compliance with the Company's policies and procedures as well as with external regulations

Finance and Spokesperson
- Corporate finance, accounting and corporate communications; with the head of the organization also serving as the Company Spokesperson

Legal
- Corporate legal affairs including regulatory compliance, commercial transactions, patents and management of other intellectual properties, and litigation

Human Resources
- Personnel management, organizational development, physical security management, employee services and wellness management

2.4 Board Members

2.4.1 Information Regarding Board Members

As of 02/28/2022

Title/Name	Gender Age	Nationality or Place of Registration	Date Elected	Term Expires	Date First Elected	Shares Held When Elected		Shares Currently Held		Shares Currently Held by Spouse & Minors		Selected Education and Professional Qualification Past Positions Current Positions at Non-profit Organizations	Selected Current Positions at TSMC and Other Companies
						Shares	%	Shares	%	Shares	%		
Chairman Mark Liu	Male 66-70	U.S.	07/26/2021	07/25/2024	06/08/2017	12,913,114	0.05%	12,913,114	0.05%	-	-	**Selected Education and Professional Qualification** Bachelor Degree in Electrical Engineering, National Taiwan University Master Degree and Ph.D. in Electrical Engineering & Computer Science, University of California, Berkeley, U.S. **Past Positions** President, Worldwide Semiconductor Manufacturing Corp. Senior Vice President, Advanced Technology Business, TSMC Senior Vice President, Operations, TSMC Executive Vice President and Co-Chief Operating Officer, TSMC President and Co-CEO, TSMC **Current Positions at Non-profit Organizations** Chairman, Taiwan Semiconductor Industry Association (TSIA)	None
Vice Chairman C.C. Wei	Male 66-70	R.O.C.	07/26/2021	07/25/2024	06/08/2017	7,179,207	0.03%	5,879,207	0.02%	700,261	0.00%	**Selected Education and Professional Qualification** Bachelor and Master Degrees in Electrical Engineering, National Chiao Tung University Ph.D. in Electrical Engineering, Yale University, U.S. **Past Positions** Senior Vice President, Chartered Semiconductor Manufacturing Ltd., Singapore Senior Vice President, Mainstream Technology Business, TSMC Senior Vice President, Business Development, TSMC Executive Vice President and Co-Chief Operating Officer, TSMC President and Co-CEO, TSMC Chairman, Taiwan Semiconductor Industry Association (TSIA)	CEO, TSMC
Director F.C. Tseng	Male 76-80	R.O.C.	07/26/2021	07/25/2024	05/13/1997	34,472,675	0.13%	29,472,675	0.11%	5,132,855	0.02%	**Selected Education and Professional Qualification** Bachelor Degree in Electrical Engineering, National Cheng Kung University Master Degree in Electrical Engineering, National Chiao Tung University Ph.D. in Electrical Engineering, National Cheng Kung University Honorary Ph.D., National Chiao Tung University Honorary Ph.D., National Tsing Hua University **Past Positions** President, Vanguard International Semiconductor Corp. President, TSMC Deputy CEO, TSMC Vice Chairman, TSMC Independent Director, Chairman of Audit Committee & Compensation Committee member, Acer Inc. Director, National Culture and Arts Foundation, R.O.C. **Current Positions at Non-profit Organizations** Chairman, TSMC Education and Culture Foundation Director, Cloud Gate Culture and Arts Foundation Director, Zu-Ming Medical Foundation	Chairman of: - TSMC China Company Ltd. (a non-public company) - Global UniChip Corp. Vice Chairman, Vanguard International Semiconductor Corp.
Director National Development Fund, Executive Yuan (Note 1) Representative: Ming-Hsin Kung	Male 56-60	R.O.C.	07/26/2021	07/25/2024	12/10/1986 07/24/2020 (Note 2)	1,653,709,980 779 (Note 2)	6.38% 0.00%	1,653,709,980 779	6.38% 0.00%	- -	- -	**Selected Education and Professional Qualification** B.A., Statistics, Fu Jen Catholic University M.A., Economics, National Taiwan University Ph.D., Economics, National Chung Hsing University **Past Positions** Adjunct Assistant Professor, Tamkang University Deputy Executive Secretary, Industrial Development Advisory Council, Ministry of Economic Affairs Research Fellow, Science and Technology Advisory Group, Executive Yuan Research Fellow, Taiwan Institute of Economic Research Vice President, Taiwan Institute of Economic Research Advisory Committee Member, Mainland Affairs Council, Executive Yuan Consultant, Ministry of Economic Affairs Member, National Stabilization Fund Management Committee, Executive Yuan Deputy Minister, National Development Council Deputy Minister, Ministry of Economic Affairs Minister without Portfolio, Executive Yuan **Current Positions at Non-profit Organizations** Minister without Portfolio, Executive Yuan & concurrently Minister, National Development Council, R.O.C.	Director, Taiwania Capital Management Corp. (Representative of the National Development Fund)

(Continued)

Title/Name	Gender Age	Nationality or Place of Registration	Date Elected	Term Expires	Date First Elected	Shares Held When Elected		Shares Currently Held		Shares Currently Held by Spouse & Minors		Selected Education and Professional Qualification Past Positions Current Positions at Non-profit Organizations	Selected Current Positions at TSMC and Other Companies
						Shares	%	Shares	%	Shares	%		
Independent Director Sir Peter L. Bonfield	Male 76-80	UK	07/26/2021	07/25/2024	05/07/2002	-	-	-	-	-	-	**Selected Education and Professional Qualification** Bachelor and Honours Degrees in Engineering, Loughborough University Fellow of the Royal Academy of Engineering Knighted, 1996 Awarded Commander of the Order of the British Empire (CBE), 1989 Awarded the Order of the Lion of Finland Awarded the Gold Medal from the Institute of Management Awarded the Mountbatten Medal from the National Electronics Council Awarded the FT ODX Outstanding Director Award, 2019 **Past Positions** Chairman and CEO, ICL Plc, UK CEO and Chairman of the Executive Committee, British Telecommunications Plc Vice President, the British Quality Foundation Director, Mentor Graphics Corp., U.S. Director, Sony Corp., Japan Director, L.M. Ericsson, Sweden Chairman, GlobalLogic Inc., U.S. Senior Advisor, Hampton Group, London Chair of Council and Senior Pro-Chancellor, Loughborough University, UK Board Member, EastWest Institute, New York	Chairman, NXP Semiconductors N.V., the Netherlands Non-Executive Director, Imagination Technologies Group Ltd., UK (a non-public company) Non-Executive Director, Darktrace Plc, UK Advisory Board Member, The Longreach Group Ltd., HK (a non-public company) Senior Advisor, Alix Partners LLP, London Board Mentor, Chairman Mentors International (CMi) Ltd., London (a non-public company)
Independent Director Kok-Choo Chen	Female 71-75	R.O.C.	07/26/2021	07/25/2024	06/09/2011	-	-	-	-	-	-	**Selected Education and Professional Qualification** Inns of Court School of Law, England Barrister-at-law, England Advocate & Solicitor, Singapore Attorney-at-law, California, U.S. **Professional Experience** Lawyer, Tan, Rajah & Cheah, Singapore, 1969-1970 Lawyer, Sullivan & Cromwell, New York, U.S., 1971-1974 Lawyer, Heller, Erhman, White & McAuliffe, San Francisco, California, U.S., 1974-1975 Partner, Ding & Ding Law Offices, R.O.C., 1975-1988 Partner, Chen & Associates Law Offices, R.O.C., 1988-1992 Vice President, Echo Publishing, R.O.C., 1992-1995 President, National Culture and Arts Foundation, R.O.C., 1995-1997 Senior Vice President and General Counsel, TSMC, 1997-2001 Founder and Executive Director, Taipei Story House, 2003-2015 Advisor, Executive Yuan, R.O.C., 2009-2016 Director, National Culture and Arts Foundation, R.O.C., 2011-2016 Chairman, National Performing Arts Center, 2014-2017 **Academic Experience** Lecturer, Nanyang University, Singapore, 1970-1971 Associate Professor, Soochow University, 1981-1998 Chair Professor, National Tsing Hua University, 1999-2002 Professor, National Chengchi University, 2001-2004 Professor, Soochow University, 2001-2008 **Current Positions at Non-profit Organizations** Founder and Executive Director, Museum207 (located in Taipei) Director, Republic of China Female Cancer Foundation	None
Independent Director Michael R. Splinter	Male 71-75	U.S.	07/26/2021	07/25/2024	06/09/2015	-	-	-	-	-	-	**Selected Education and Professional Qualification** Bachelor and Master Degrees in Electrical Engineering, University of Wisconsin-Madison Honorary Ph. D in Engineering, University of Wisconsin-Madison Awarded 2013 Robert N. Noyce Award by Semiconductor Industry Association Recognized as NACD (National Association of Corporate Directors) Directorship Certified™, 2020 **Past Positions** Executive Vice President of Technology and Manufacturing group, Intel Corp. Executive Vice President of Sales and Marketing, Intel Corp. CEO, Applied Materials, Inc. Chairman, Applied Materials, Inc. Director, The NASDAQ OMX Group, Inc. Director, Silicon Valley Leadership Group Director, Semiconductor Equipment and Materials International (SEMI) Director, Meyer Burger Technology Ltd., Switzerland Director, University of Wisconsin Foundation, U.S. **Current Positions at Non-profit Organizations** Chairman of the Board, US-Taiwan Business Council	Chairman of the Board, NASDAQ, Inc. Director of: - Pica8, Inc., U.S. (a non-public company) - Gogoro Inc., Cayman Islands (a non-public company) - Tigo Energy, Inc., U.S. (a non-public company) - Kioxia Holdings Corp., Japan (a non-public company) General Partner, WISC Partners LP, U.S.

(Continued)

Title/Name	Gender Age	Nationality or Place of Registration	Date Elected	Term Expires	Date First Elected	Shares Held When Elected		Shares Currently Held		Shares Currently Held by Spouse & Minors		Selected Education and Professional Qualification Past Positions Current Positions at Non-profit Organizations	Selected Current Positions at TSMC and Other Companies
						Shares	%	Shares	%	Shares	%		
Independent Director Moshe N. Gavrielov	Male 66-70	U.S.	07/26/2021	07/25/2024	06/05/2019	-	-	-	-	-	-	Selected Education and Professional Qualification Bachelor Degree in Electrical Engineering, Technion - Israel Institute of Technology Master Degree in Computer Science, Technion - Israel Institute of Technology Past Positions In a variety of engineering and engineering management positions, National Semiconductor Corp. and Digital Equipment Corp., U.S. In a variety of executive management positions, LSI Logic Corp. for nearly 10 years, U.S. CEO, Verisity, Ltd., U.S. Executive Vice President and General Manager of the Verification Division, Cadence Design Systems, Inc., U.S. President and CEO, Xilinx, Inc., U.S. Director, Xilinx, Inc., U.S. Current Positions at Non-profit Organizations Director, San Jose Institute of Contemporary Art, U.S.	Executive Chairman, Wind River Systems, Inc., U.S. (a non-public company) Chairman, SiMa Technologies, Inc., U.S. (a non-public company) Chairman, Foretellix, Ltd., Israel (a non-public company)
Independent Director Yancey Hai	Male 71-75	R.O.C. U.S.	07/26/2021	07/25/2024	06/09/2020	-	-	-	-	-	-	Selected Education and Professional Qualification M.A., International Business Management, University of Texas at Dallas Past Positions Country Manager, GE Capital Taiwan Vice Chairman and CEO, Delta Electronics, Inc. Chair, Strategic Steering Committee, Delta, 2012-2021 Current Positions at Non-profit Organizations Executive Director, Taipei Computer Association Senior Strategy Consultant, Cloud Computing & IoT Association in Taiwan Director, Taiwan Business Council for Sustainable Development Director, Delta Electronic Foundation Director, Felix Chang Foundation	Chairman, Delta Electronics, Inc. (Delta), 2012- Chair of ESG Committee, Delta Director of Delta's subsidiaries: - Delta Electronics (Shanghai) Co., Ltd. (a non-public company) - Delta Networks, Inc. (a non-public company) - Delta Electronics Capital Company (a non-public company) - Cyntec Co., Ltd. (a non-public company) Independent Director, Audit Committee member, Chair and member of Remuneration Committee, and CSR Committee member, USI Corporation Director and Commissioner of ESG & Net Zero Committee, CTCI Corporation
Independent Director L. Rafael Reif (Note 3)	Male 71-75	U.S.	07/26/2021	07/25/2024	07/26/2021	-	-	-	-	-	-	Selected Education and Professional Qualification Ingeniero Eléctrico Degree, Universidad de Carabobo, Valencia, Venezuela Master Degree and Ph.D. in Electrical Engineering, Stanford University Honorary Doctor of Laws degree, The Chinese University of Hong Kong (2015) Honorary Doctorates from Tsinghua University (2016), the Technion (2017) and Arizona State University (2018) Member of Tau Beta Pi, the Engineering Honor Society Member of the Electrochemical Society Fellow of the Institute of Electrical and Electronics Engineers (IEEE) Member of the American Academy of Arts and Sciences, the National Academy of Engineering and the Chinese Academy of Engineering Fellow of the National Academy of Inventors Awarded with United States Presidential Young Investigator Award (1984) Awarded with the Semiconductor Research Corporation's Aristotle Award (2000) Awarded with Engineer of the Year from Great Minds in STEM (2018) Inventor or co-inventor on 13 patents, editor or Co-editor of 5 books, and supervisor to 38 doctoral theses Past Positions Assistant Professor, Universidad Simón Bolívar, Caracas, Venezuela Visiting Assistant Professor of Electrical Engineering, Stanford University Faculty, Massachusetts Institute of Technology (MIT), since 1980 IBM Faculty Fellowship, MIT Center for Materials Science and Engineering; Analog Devices Career Development Professorship, MIT Electrical Engineering. Fariborz Maseeh Professor of Emerging Technology, MIT (2004-2012) Director of Microsystems Technology Laboratories, MIT Associate Department Head of Electrical Engineering, MIT Head of the Department of Electrical Engineering and Computer Science (EECS), MIT Provost, MIT Board Director, Schlumberger Limited Current Positions at Non-profit Organizations President, MIT, since 2012	Co-Chair of Growth Technical Advisory Board, Applied Materials, Inc.

Remarks:
1. No member of the Board of Directors held TSMC shares by nominee arrangement.
2. Managers or Directors who are spouses or within second-degree relative of consanguinity to the directors: None.
3. Chairman and President (or someone with an equivalent job responsibility, i.e. the highest ranking manager of the company) are not (1) the same person, (2) in a marital relationship with each other, or (3) within one degree of consanguinity.

Note 1: Major Shareholders of the Institutional Shareholder

Institutional Shareholder	Major Shareholders (Top 10 Shareholders) of the Institutional Shareholder
National Development Fund, Executive Yuan	Not Applicable

Note 2: Mr. Ming-Hsin Kung was appointed as the representative of National Development Fund on July 24, 2020.
Note 3: Dr. L. Rafael Reif was elected as TSMC's independent director at TSMC's Annual Shareholders' Meeting on July 26, 2021.

2.4.2 Remuneration Paid to Directors and Independent Directors (Note 1)

Unit: NT$

Title/Name	Director's Remuneration								(A+B+C+D) as a % of Net Income		Compensation Earned by a Director Who is an Employee of TSMC or of TSMC's Consolidated Entities								(A+B+C+D+E+F+G) as a % of Net Income (Note 6)		Compensation Paid to Directors from Non-consolidated Affiliates or Parent Company
	Base Compensation (A)		Severance Pay and Pensions (B) (Note 4)		Compensation to Directors (C)		Allowances (D) (Note 5)				Base Compensation, Bonuses, and Allowances (E) (Note 5)		Severance Pay and Pensions (F) (Note 4)		Profit Sharing (G)						
															From TSMC		From All Consolidated Entities				
	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	Cash	Stock (Fair Market Value)	Cash	Stock (Fair Market Value)	From TSMC	From All Consolidated Entities	
Chairman Mark Liu	16,844,157	16,844,157	212,600	212,600	381,903,540	381,903,540	1,416,161	1,416,161	0.0671%	0.0671%	-	-	-	-	-	-	-	-	0.0671%	0.0671%	-
Vice Chairman C.C. Wei	-	-	-	-	-	-	-	-	-	-	209,137,587	209,137,587	212,600	212,600	190,951,770	-	190,951,770	-	0.0671%	0.0671%	-
Director F.C. Tseng	-	-	-	-	10,560,000	10,560,000	1,294,800	1,294,800	0.0020%	0.0020%	-	-	-	-	-	-	-	-	0.0020%	0.0020%	11,000,643
Director National Development Fund, Executive Yuan Representative: Ming-Hsin Kung	-	-	-	-	10,560,000	10,560,000	-	-	0.0018%	0.0018%	-	-	-	-	-	-	-	-	0.0018%	0.0018%	-
Independent Director Sir Peter L. Bonfield	-	-	-	-	14,754,872	14,754,872	-	-	0.0025%	0.0025%	-	-	-	-	-	-	-	-	0.0025%	0.0025%	-
Independent Director Stan Shih (Note 2)	-	-	-	-	7,487,097	7,487,097	-	-	0.0013%	0.0013%	-	-	-	-	-	-	-	-	0.0013%	0.0013%	-
Independent Director Kok-Choo Chen	-	-	-	-	13,200,000	13,200,000	-	-	0.0022%	0.0022%	-	-	-	-	-	-	-	-	0.0022%	0.0022%	-
Independent Director Michael R. Splinter	-	-	-	-	14,754,872	14,754,872	-	-	0.0025%	0.0025%	-	-	-	-	-	-	-	-	0.0025%	0.0025%	-
Independent Director Moshe N. Gavrielov	-	-	-	-	14,754,872	14,754,872	-	-	0.0025%	0.0025%	-	-	-	-	-	-	-	-	0.0025%	0.0025%	-
Independent Director Yancey Hai	-	-	-	-	13,200,000	13,200,000	-	-	0.0022%	0.0022%	-	-	-	-	-	-	-	-	0.0022%	0.0022%	-
Independent Director L. Rafael Reif (Note 3)	-	-			6,361,376	6,361,376			0.0011%	0.0011%									0.0011%	0.0011%	
Total	16,844,157	16,844,157	212,600	212,600	487,536,629	487,536,629	2,710,961	2,710,961	0.0850%	0.0850%	209,137,587	209,137,587	212,600	212,600	190,951,770	-	190,951,770	-	0.1521%	0.1521%	11,000,643

*Other than disclosure in the above table, Directors remunerations earned by providing services (e.g. providing consulting services as a non-employee of parent company/all consolidated entities/non-consolidated affiliates) to TSMC and all consolidated entities in the 2021 financial statements: Dr. F.C. Tseng for NT$15,119,043.

Note 1: Directors and Independent Directors' remuneration policies, procedures, standards and structure, as well as the linkage to responsibilities, risks and time spent:

- According to TSMC's Articles of Incorporation, the Board of Directors is authorized to determine the salary for the Chairman, Vice Chairman and Directors, taking into account the extent and value of the services provided for the management of the Corporation and the standards of the industry within the R.O.C. and overseas.
- The Articles of Incorporation also provide that the compensation to directors shall be no more than 0.3% of annual profits and directors who also serve as executive officers of TSMC are not entitled to receive compensation to directors. According to TSMC's Compensation Committee Charter, the distribution of compensation to directors shall be made in accordance with TSMC's "Rules for Distribution of Compensation to Directors" based on the following principles: (1) directors who also serve as executive officers of the Company are not entitled to receive compensation; (2) the compensation for independent directors may be higher than the other directors, as all independent directors also serve as members of the Audit Committee and the Compensation Committee and thus participate in the discussions as well as resolutions of related committee meetings in accordance with the charter of each committee; and (3) the compensation for overseas independent directors may be higher than domestic independent directors, as they require additional time to attend quarterly meetings in Taiwan.

Note 2: Mr. Stan Shih's tenure expired on July 26, 2021 because he was not re-elected at the 2021 Annual Shareholders' Meeting.
Note 3: Dr. L. Rafael Reif was elected as TSMC's independent director at TSMC's Annual Shareholders' Meeting on July 26, 2021.
Note 4: Pensions funded according to applicable law.
Note 5: The above-mentioned figures include expenses for Company cars and related reimbursements, but do not include compensation paid to Company drivers (totaled NT$4,142,123).
Note 6: Total remuneration paid to the directors from TSMC and from all consolidated entities in 2020, including their employee compensation, both accounted for 0.1832% of 2020 net income.

2.5 Management Team

2.5.1 Information Regarding Management Team

As of 02/28/2022

Title Name	Gender	Nationality	On-board Date (Note 1)	Shares Held		Shares Held by Spouse & Minors		Shares Held in the Name of Others		Education and Selected Past Positions	Selected Current Positions at Other Companies	Managers Who are Spouses or within Second-degree Relative of Consanguinity to Each Other (Note 2)		
				Shares	%	Shares	%	Shares	%			Title	Name	Relation
Chief Executive Officer C.C. Wei	Male	R.O.C.	02/01/1998	5,879,207	0.02%	700,261	0.00%	-	-	Ph.D., Electrical Engineering, Yale University, U.S. President and Co-Chief Executive Officer, TSMC Executive Vice President and Co-Chief Operating Officer, TSMC Senior Vice President, Business Development, TSMC Senior Vice President, Mainstream Technology Business, TSMC Senior Vice President, Chartered Semiconductor Manufacturing Ltd.	None	None	None	None
Senior Vice President Europe & Asia Sales and Human Resources Lora Ho	Female	R.O.C.	06/01/1999	4,570,080	0.02%	2,230,268	0.01%	-	-	Master, Business Administration, National Taiwan University, Taiwan Senior Vice President, Chief Financial Officer/Spokesperson, TSMC Senior Director, Accounting, TSMC Vice President & CFO, TI-Acer Semiconductor Manufacturing Corp.	Director and/or Supervisor, TSMC subsidiaries	None	None	None
Senior Vice President Research and Development Wei-Jen Lo	Male	R.O.C.	07/01/2004	1,441,127	0.01%	-	-	-	-	Ph.D., Solid State Physics and Surface Chemistry, University of California, Berkeley, U.S. Vice President, Technology Development, TSMC Vice President, Manufacturing Technology, TSMC Vice President, Advanced Technology Business, TSMC Vice President, Operations II, TSMC Director, Advanced Technology Development and CTM Plant Manager, Intel Corp.	None	None	None	None
Senior Vice President Corporate Strategy Office CEO & President TSMC Arizona Rick Cassidy	Male	U.S.	11/14/1997	-	-	-	-	-	-	Bachelor, Engineering Technology, United States Military Academy at West Point, U.S. Chief Executive Officer, TSMC North America President, TSMC North America Vice President, TSMC North America	President and CEO, TSMC subsidiary	None	None	None
Senior Vice President Operations Y.P. Chin	Male	R.O.C.	01/01/1987	6,920,122	0.03%	2,191,107	0.01%	-	-	Master, Electrical Engineering, National Cheng Kung University, Taiwan Senior Vice President, Product Development, TSMC Vice President, Advanced Technology and Business, TSMC	Director, TSMC subsidiaries	None	None	None
Senior Vice President Research and Development Y.J. Mii	Male	R.O.C.	11/14/1994	1,000,419	0.00%	-	-	-	-	Ph.D., Electrical Engineering, University of California, Los Angeles, U.S. Vice President, Technology Development, TSMC Senior Director, Platform I Division, TSMC	None	Director	Wayne Yeh	Brother in law
Senior Vice President Information Technology and Materials Management & Risk Management J.K. Lin	Male	R.O.C.	01/01/1987	12,648,251	0.05%	1,019,961	0.00%	-	-	Bachelor, Science, National Changhua University of Education, Taiwan Vice President, Mainstream Fabs and Manufacturing Technology, TSMC Senior Director, Mainstream Fabs, TSMC	None	None	None	None
Senior Vice President Corporate Planning Organization J.K. Wang	Male	R.O.C.	02/11/1987	2,603,947	0.01%	160,844	0.00%	-	-	Master, Chemical Engineering, National Cheng Kung University, Taiwan Senior Vice President, Fab Operations, TSMC Vice President, 300mm Fabs, TSMC Senior Director, 300mm Fabs, TSMC	None	None	None	None
Senior Vice President Europe & Asia Sales and Research & Development/ Corporate Research Cliff Hou	Male	R.O.C.	12/15/1997	384,676	0.00%	60,802	0.00%	-	-	Ph.D., Electrical Engineering, Syracuse University, U.S. Senior Vice President, Technology Development, TSMC Vice President, Design and Technology Platform, TSMC Senior Director, Design and Technology Platform, TSMC	Director and/or President, TSMC subsidiaries Director, TSMC affiliate	None	None	None
Senior Vice President Business Development Kevin Zhang	Male	U.S.	11/01/2016	70,000	0.00%	-	-	-	-	Ph.D., Electrical Engineering, Duke University, U.S. Vice President, Design and Technology Platform, TSMC Vice President, Technology and Manufacturing Group, Intel Corp.	None	None	None	None
Vice President and General Counsel Corporate Governance Officer Legal Sylvia Fang	Female	R.O.C.	03/20/1995	700,285	0.00%	67,906	0.00%	384,000	0.00%	Master, Comparative Law, School of Law, University of Iowa, U.S. Attorney-at-law, Taiwan Associate General Counsel, TSMC Senior Associate, Taiwan International Patent and Law Office (TIPLO)	Director and/or Supervisor, TSMC subsidiaries	None	None	None
Vice President Human Resources Connie Ma	Female	R.O.C.	06/01/2014	236,000	0.00%	-	-	-	-	EMBA, International Business Management, National Taiwan University Director, Human Resources, TSMC Senior Vice President, Global Human Resources, Trend Micro Inc.	None	None	None	None
Vice President Operations/Fab Operations I Y.L. Wang	Male	R.O.C	06/01/1992	218,535	0.00%	1,135,529	0.00%	-	-	Ph.D., Electrical Engineering, National Chiao Tung University, Taiwan Vice President, Fab Operations, TSMC Vice President, Technology Development, TSMC Vice President, Fab 14B, TSMC Senior Director, Fab 14B, TSMC	Director, TSMC subsidiary	None	None	None
Vice President and TSMC Distinguished Fellow Pathfinding for System Integration Doug Yu	Male	R.O.C.	12/28/1994	250,000	0.00%	-	-	-	-	Ph.D., Materials Engineering, Georgia Institute of Technology, U.S. Vice President, Integrated Interconnect & Packaging, TSMC Senior Director, Integrated Interconnect & Packaging Division, TSMC	None	None	None	None
Vice President and TSMC Fellow Operations/Advanced Technology and Mask Engineering T.S. Chang	Male	R.O.C.	02/06/1995	173,781	0.00%	-	-	-	-	Ph.D., Electrical Engineering, National Tsing Hua University, Taiwan Vice President, Product Development, TSMC Vice President, Fab 12B, TSMC Senior Director, Fab 12B, TSMC	None	None	None	None

(Continued)

Title Name	Gender	Nationality	On-board Date (Note 1)	Shares Held		Shares Held by Spouse & Minors		Shares Held in the Name of Others		Education and Selected Past Positions	Selected Current Positions at Other Companies	Managers Who are Spouses or within Second-degree Relative of Consanguinity to Each Other (Note 2)		
				Shares	%	Shares	%	Shares	%			Title	Name	Relation
Vice President Research and Development/Platform Development Michael Wu	Male	R.O.C.	12/09/1996	483,501	0.00%	194,943	0.00%	-	-	Ph.D., Electrical Engineering, University of Wisconsin-Madison, U.S. Senior Director, Platform Development, TSMC	None	None	None	None
Vice President Research and Development/Pathfinding Min Cao	Male	U.S.	07/29/2002	363,152	0.00%	4,470	0.00%	-	-	Ph.D., Physics, Stanford University, U.S. Senior Director, Pathfinding Division, TSMC	None	None	None	None
Vice President Operations/Advanced Packaging Technology and Service Marvin Liao	Male	R.O.C.	06/06/2002	90,485	0.00%	-	-	235,000	0.00%	Ph.D., Materials Science, University of Texas-Arlington, U.S. Senior Director, Backend Technology and Service Division, TSMC Vice President, Chartered Semiconductor Manufacturing Ltd.	Director, TSMC subsidiary	None	None	None
Vice President Operations/Fab Operations II Y.H. Liaw	Male	R.O.C.	08/03/1988	370,000	0.00%	-	-	430,000	0.00%	Master, Chemical Engineering, National Tsing Hua University, Taiwan Vice President, Fab Operations, TSMC Vice President, Fab 15B, TSMC Senior Director, Fab 15B, TSMC	Director, TSMC subsidiaries Director, TSMC affiliate	None	None	None
Vice President Research and Development/Advanced Tool and Module Development Simon Jang	Male	R.O.C.	09/01/1993	350,695	0.00%	663	0.00%	-	-	Ph.D., Materials Science & Engineering, Massachusetts Institute of Technology, U.S. Senior Director, Advanced Tool and Module Development Division, TSMC	None	1. Deputy Director 2. Manager	1. Sharon Jang 2. Jimmy Hu	1. Sister 2. Brother in law
Vice President and Chief Financial Officer Spokesperson Finance Wendell Huang	Male	R.O.C.	05/03/1999	1,651,756	0.01%	-	-	-	-	Master, Business Administration, Cornell University, U.S. Deputy Chief Financial Officer, TSMC Senior Director, Finance Division, TSMC Vice President, Corporate Finance, ING Barings Vice President, Corporate Finance, Chase Manhattan Bank Vice President, Corporate Finance, Bankers Trust Company	Director, Supervisor, and/or President, TSMC subsidiaries Director, TSMC affiliate	None	None	None
Vice President Research and Development/More than Moore Technologies C.S. Yoo	Male	R.O.C.	06/16/1988	1,703,690	0.01%	219,924	0.00%	851,908	0.00%	Ph.D., Chemical Engineering, Worcester Polytech. Institute, U.S. Senior Director, Office of Strategy Customer Program, TSMC Senior Director, E-Beam Operation Division, TSMC	None	None	None	None
Vice President Quality and Reliability Jun He	Male	U.S.	05/22/2017	9,000	0.00%	-	-	-	-	Ph.D., Materials Science and Engineering, University of California, Santa Barbara, U.S. Senior Director, Quality and Reliability, TSMC Senior Director, Head of Quality and Reliability for Technology & Manufacturing Group, Intel Corp.	None	None	None	None
Vice President Research and Development/Platform Development Geoffrey Yeap	Male	U.S.	03/21/2016	22,000	0.00%	-	-	-	-	Ph.D., Electrical and Computer Engineering, University of Texas-Austin, U.S. Senior Director, Platform Development, TSMC Senior Director, Advanced Technology, TSMC Vice President, Engineering, Silicon Technology, Qualcomm	None	None	None	None
Vice President and Chief Information Officer Information Technology and Materials Management & Risk Management/Corporate Information Technology Chris Horng-Dar Lin	Male	U.S.	01/04/2021	16,000	0.00%	-	-	-	-	Ph.D., Electrical Engineering and Computer Science, University of California, Berkeley, U.S. Vice President, Information Technology, Mozilla Director, Enterprise Platform Infrastructure, Facebook	None	None	None	None
Vice President Corporate Planning Organization Jonathan Lee (Note 3)	Male	R.O.C.	05/28/2007	334,458	0.00%	-	-	-	-	Master, Business Administration, City University of New York, Baruch College, U.S. Senior Director, Strategic Planning Division, TSMC	None	None	None	None
Vice President Operations/Facility Arthur Chuang (Note 4)	Male	R.O.C.	01/17/1989	2,602,981	0.01%	1,993,040	0.01%	-	-	Ph.D., Civil Engineering, National Taiwan University, Taiwan Senior Director, Facility Division, TSMC	None	Section Manager	Gavin Chuang	Brother
Vice President and TSMC Fellow Research and Development/Design & Technology Platform L.C. Lu (Note 5)	Male	R.O.C.	08/01/2000	130,227	0.00%	10,000	0.00%	-	-	Ph.D., Computer Science, Yale University, U.S. Senior Director, Digital IPs Solution Division, TSMC	None	None	None	None
Vice President Research and Development/Integrated Interconnect & Packaging K.C. Hsu (Note 6)	Male	R.O.C.	11/01/2021	16,000	0.00%	-	-	-	-	Master, Technology Management, National Chiao Tung University, Taiwan Taiwan Country Manager, Micron Technology Inc. President, WaferTech LLC	None	None	None	None

Note 1: On-board date means the official date joining TSMC.
Note 2: President (or someone with an equivalent job responsibility, i.e. the highest ranking manager of the company) and Chairman are not (1) the same person, (2) in a marital relationship with each other, or (3) within one degree of consanguinity.
Note 3: Mr. Jonathan Lee was promoted to Vice President, effective June 9, 2021.
Note 4: Dr. Arthur Chuang was promoted to Vice President, effective August 10, 2021.
Note 5: Dr. L.C. Lu was promoted to Vice President, effective August 10, 2021.
Note 6: Mr. K.C. Hsu was promoted to Vice President, effective November 9, 2021.

2.5.2 Compensation Paid to CEO and Vice Presidents (Note 1)

Unit: NT$

Title	Name	Salary (A)		Severance Pay and Pensions (B) (Note 6)		Bonuses and Allowances (C) (Note 7)		Profit Sharing (D)				(A+B+C+D) as a % of Net Income (Note 8)		Compensation Received from Non-consolidated Affiliates or Parent Company
								From TSMC		From All Consolidated Entities				
		From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	Cash	Stock (Fair Market Value)	Cash	Stock (Fair Market Value)	From TSMC	From All Consolidated Entities	
Chief Executive Officer	C.C. Wei	13,287,420	13,287,420	212,600	212,600	195,850,167	195,850,167	190,951,770	-	190,951,770	-	0.0671%	0.0671%	-
Vice President, Chief Financial Officer/Spokesperson	Wendell Huang	5,240,260	5,240,260	83,844	83,844	28,595,054	28,595,054	27,170,780	-	27,170,780	-	0.0102%	0.0102%	-
Senior Vice President	Lora Ho	122,544,351	137,629,064	1,948,517	2,390,511	861,047,137	964,023,195	812,804,670	-	812,804,670	-	0.3015%	0.3213%	-
Senior Vice President	Wei-Jen Lo													
Senior Vice President/CEO & President of TSMC Arizona	Rick Cassidy													
Senior Vice President	Y.P. Chin													
Senior Vice President	Y.J. Mii													
Senior Vice President	J.K. Lin													
Senior Vice President	J.K. Wang													
Senior Vice President	Cliff Hou													
Senior Vice President	Kevin Zhang													
Vice President and General Counsel/Corporate Governance Officer	Sylvia Fang													
Vice President	Connie Ma													
Vice President	Y.L. Wang													
Vice President and TSMC Distinguished Fellow	Doug Yu													
Vice President and TSMC Fellow	T.S. Chang													
Vice President	Michael Wu													
Vice President	Min Cao													
Vice President	Marvin Liao													
Vice President	Y.H. Liaw													
Vice President	Simon Jang													
Vice President	C.S. Yoo													
Vice President	Jun He													
Vice President	Geoffrey Yeap (Note 2)													
Vice President and Chief Information Officer	Chris Horng-Dar Lin (Note 2)													
Vice President	Jonathan Lee (Note 3)													
Vice President	Arthur Chuang (Note 4)													
Vice President and TSMC Fellow	L.C. Lu (Note 4)													
Vice President	K.C. Hsu (Note 5)													
Total		141,072,031	156,156,744	2,244,961	2,686,955	1,085,492,358	1,188,468,416	1,030,927,220	-	1,030,927,220	-	0.3788%	0.3987%	-

Note 1: Compensation policy, standards/packages, procedures, the linkage to operating performance and future risk exposure: The total compensation paid to the executive officers is based on their job responsibility, contribution, company performance, and projected future risks the Company will face. It is reviewed by the Compensation Committee then submitted to the Board of Directors for approval.
Note 2: Dr. Geoffrey Yeap and Dr. Chris Horng-Dar Lin were promoted to Vice President, effective February 9, 2021. These amounts did not include compensation for the period before their promotion.
Note 3: Mr. Jonathan Lee was promoted to Vice President, effective June 9, 2021. These amounts did not include compensation for the period before his promotion.
Note 4: Dr. Arthur Chuang and Dr. L.C. Lu were promoted to Vice President, effective August 10, 2021. These amounts did not include compensation for the period before their promotion.
Note 5: Mr. K.C. Hsu was promoted to Vice President, effective November 9, 2021. These amounts did not include compensation for the period before his promotion.
Note 6: Pensions funded according to applicable law.
Note 7: The above-mentioned figures include the expense for the business performance bonuses distributed in May, August, November 2021 & February 2022, and Company cars and gasoline reimbursements.
Note 8: Total compensation paid to the executive officers from TSMC in 2020 accounted for 0.3939% of 2020 net income. Total compensation paid to the executive officers from all consolidated entities in 2020 accounted for 0.4131% of 2020 net income.

Compensation Paid to CEO and Vice Presidents

	2021	
	From TSMC	From All Consolidated Entities and Non-consolidated Affiliates
NT$0 ~ NT$999,999	Rick Cassidy	None
NT$1,000,000 ~ NT$1,999,999	None	None
NT$2,000,000 ~ NT$3,499,999	None	None
NT$3,500,000 ~ NT$4,999,999	None	None
NT$5,000,000 ~ NT$9,999,999	K.C. Hsu	K.C. Hsu
NT$10,000,000 ~ NT$14,999,999	None	None
NT$15,000,000 ~ NT$29,999,999	Jonathan Lee, Arthur Chuang, L.C. Lu	Jonathan Lee, Arthur Chuang, L.C. Lu
NT$30,000,000 ~ NT$49,999,999	Simon Jang, Jun He, Geoffrey Yeap, Chris Horng-Dar Lin	Simon Jang, Jun He, Geoffrey Yeap, Chris Horng-Dar Lin
NT$50,000,000 ~ NT$99,999,999	Wendell Huang, J.K. Wang, Kevin Zhang, Sylvia Fang, Connie Ma, Y.L. Wang, Doug Yu, T.S. Chang, Michael Wu, Min Cao, Marvin Liao, Y.H. Liaw, C.S. Yoo	Wendell Huang, J.K. Wang, Kevin Zhang, Sylvia Fang, Connie Ma, Y.L. Wang, Doug Yu, T.S. Chang, Michael Wu, Min Cao, Marvin Liao, Y.H. Liaw, C.S. Yoo
Over NT$100,000,000	C.C. Wei, Lora Ho, Wei-Jen Lo, Y.P. Chin, Y.J. Mii, J.K. Lin, Cliff Hou	C.C. Wei, Lora Ho, Wei-Jen Lo, Rick Cassidy, Y.P. Chin, Y.J. Mii, J.K. Lin, Cliff Hou
Total	29	29

2.5.3 Employees' Profit Sharing Paid to Management Team

Unit: NT$

Title	Name	Stock (Fair Market Value)	Cash	Total	Total Profit Sharing Paid to Management Team as a % of Net Income
Chief Executive Officer	C.C. Wei	-	190,951,770	190,951,770	0.0320%
Vice President, Chief Financial Officer/Spokesperson	Wendell Huang	-	27,170,780	27,170,780	0.0046%
Senior Vice President	Lora Ho				
Senior Vice President	Wei-Jen Lo				
Senior Vice President/ CEO & President of TSMC Arizona	Rick Cassidy				
Senior Vice President	Y.P. Chin				
Senior Vice President	Y.J. Mii				
Senior Vice President	J.K. Lin				
Senior Vice President	J.K. Wang				
Senior Vice President	Cliff Hou				
Senior Vice President	Kevin Zhang				
Vice President and General Counsel/Corporate Governance Officer	Sylvia Fang				
Vice President	Connie Ma				
Vice President	Y.L. Wang				
Vice President and TSMC Distinguished Fellow	Doug Yu				
Vice President and TSMC Fellow	T.S. Chang	-	812,804,670	812,804,670	0.1363%
Vice President	Michael Wu				
Vice President	Min Cao				
Vice President	Marvin Liao				
Vice President	Y.H. Liaw				
Vice President	Simon Jang				
Vice President	C.S. Yoo				
Vice President	Jun He				
Vice President	Geoffrey Yeap (Note 1)				
Vice President and Chief Information Officer	Chris Horng-Dar Lin (Note 1)				
Vice President	Jonathan Lee (Note 2)				
Vice President	Arthur Chuang (Note 3)				
Vice President and TSMC Fellow	L.C. Lu (Note 3)				
Vice President	K.C. Hsu (Note 4)				
Total		-	1,030,927,220	1,030,927,220	0.1728%

Note 1: Dr. Geoffrey Yeap and Dr. Chris Horng-Dar Lin were promoted to Vice President, effective February 9, 2021. These amounts did not include compensation for the period before their promotion.
Note 2: Mr. Jonathan Lee was promoted to Vice President, effective June 9, 2021. These amounts did not include compensation for the period before his promotion.
Note 3: Dr. Arthur Chuang and Dr. L.C. Lu were promoted to Vice President, effective August 10, 2021. These amounts did not include compensation for the period before their promotion. Therefore, their 2020 compensation data are not disclosed.
Note 4: Mr. K.C. Hsu was promoted to Vice President, effective November 9, 2021. These amounts did not include compensation for the period before his promotion.